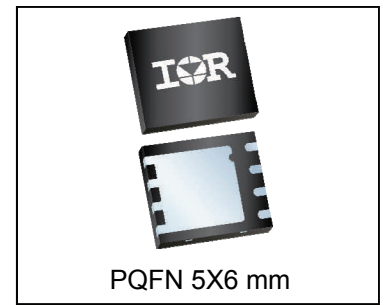
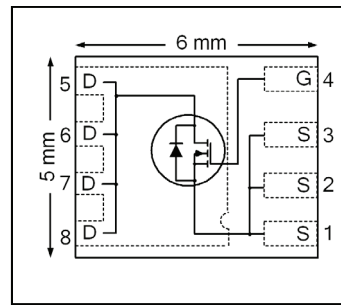


HEXFET® Power MOSFET

|  |     |            |
|--|-----|------------|
| $V_{DSS}$                                  | 100 | V          |
| $R_{DS(on) \max}$<br>(@ $V_{GS} = 10V$ )   | 3.9 | m $\Omega$ |
| $Q_g$ (typical)                            | 49  | nC         |
| $R_g$ (typical)                            | 0.9 | $\Omega$   |
| $I_D$<br>(@ $T_{C(Bottom)} = 25^\circ C$ ) | 157 | A          |



### Applications

- Optimized for Secondary Side Synchronous Rectification
- Primary Switch for High Frequency 48V/60V Telecom DC-DC Power Supplies
- Hot Swap and Active O-Ring
- BLDC Motor Drive

### Features

|   |
|---|
| Low $R_{DS(ON)}$ (<3.9m $\Omega$ )                  |
| Low Thermal Resistance to PCB (<0.64 $^\circ C/W$ ) |
| 100% $R_g$ Tested                                   |
| Low Profile (<1.05 mm)                              |
| Industry-Standard Pinout                            |
| Compatible with Existing Surface Mount Techniques   |
| RoHS Compliant, Halogen-Free                        |
| MSL1  |

results in  
⇒

### Benefits

|                            |
|----------------------------|
| Lower Conduction Losses    |
| Increased Power Density    |
| Increased Reliability      |
| Increased Power Density    |
| Multi-Vendor Compatibility |
| Easier Manufacturing       |
| Environmentally Friendlier |
| Increased Reliability      |

| Base part number | Package Type    | Standard Pack |          | Orderable Part Number |
|------------------|-----------------|---------------|----------|-----------------------|
|                  |                 | Form          | Quantity |                       |
| IRFH7182PbF      | PQFN 5mm x 6 mm | Tape and Reel | 4000     | IRFH7182TRPbF         |

### Absolute Maximum Ratings

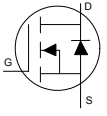
|                                     | Parameter   | Max.         | Units         |
|-------------------------------------|---|--------------|---------------|
| $V_{GS}$                            | Gate-to-Source Voltage                              | $\pm 20$     | V             |
| $I_D @ T_A = 25^\circ C$            | Continuous Drain Current, $V_{GS} @ 10V$            | 23           | A             |
| $I_D @ T_{C(Bottom)} = 25^\circ C$  | Continuous Drain Current, $V_{GS} @ 10V$            | 157          |               |
| $I_D @ T_{C(Bottom)} = 100^\circ C$ | Continuous Drain Current, $V_{GS} @ 10V$            | 99           |               |
| $I_{DM}$                            | Pulsed Drain Current ①                              | 320          |               |
| $P_D @ T_A = 25^\circ C$            | Power Dissipation                                   | 4.0          | W             |
| $P_D @ T_{C(Bottom)} = 25^\circ C$  | Power Dissipation                                   | 195          |               |
|                                     | Linear Derating Factor                              | 0.03         | W/ $^\circ C$ |
| $T_J$<br>$T_{STG}$                  | Operating Junction and<br>Storage Temperature Range | -55 to + 150 | $^\circ C$    |

Notes ① through ⑤ are on page 8

**Static @ T<sub>J</sub> = 25°C (unless otherwise specified)**

|                                     | Parameter   | Min. | Typ. | Max. | Units | Conditions  |
|-------------------------------------|---|------|------|------|-------|---|
| BV <sub>DSS</sub>                   | Drain-to-Source Breakdown Voltage                   | 100  | —    | —    | V     | V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA  |
| ΔBV <sub>DSS</sub> /ΔT <sub>J</sub> | Breakdown Voltage Temp. Coefficient                 | —    | 62   | —    | mV/°C | Reference to 25°C, I <sub>D</sub> = 1mA   |
| R <sub>DS(on)</sub>                 | Static Drain-to-Source On-Resistance                | —    | 3.1  | 3.9  | mΩ    | V <sub>GS</sub> = 10V, I <sub>D</sub> = 50A ③   |
| V <sub>GS(th)</sub>                 | Gate Threshold Voltage                              | 2.0  | —    | 3.6  | V     | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA                                    |
| ΔV <sub>GS(th)</sub>                | Gate Threshold Voltage Coefficient                  | —    | -5.3 | —    | mV/°C |   |
| I <sub>DSS</sub>                    | Drain-to-Source Leakage Current                     | —    | —    | 1.0  | μA    | V <sub>DS</sub> = 80V, V <sub>GS</sub> = 0V   |
| I <sub>GSS</sub>                    | Gate-to-Source Forward Leakage                      | —    | —    | 100  | nA    | V <sub>GS</sub> = 20V   |
|                                     | Gate-to-Source Reverse Leakage                      | —    | —    | -100 |       | V <sub>GS</sub> = -20V  |
| g <sub>fs</sub>                     | Forward Transconductance                            | 135  | —    | —    | S     | V <sub>DS</sub> = 25V, I <sub>D</sub> = 50A   |
| Q <sub>g</sub>                      | Total Gate Charge                                   | —    | 49   | 74   | nC    | V <sub>DS</sub> = 50V<br>V <sub>GS</sub> = 10V<br>I <sub>D</sub> = 50A                        |
| Q <sub>gs1</sub>                    | Pre-V <sub>th</sub> Gate-to-Source Charge           | —    | 9.3  | —    |       |   |
| Q <sub>gs2</sub>                    | Post-V <sub>th</sub> Gate-to-Source Charge          | —    | 3.1  | —    |       |   |
| Q <sub>gd</sub>                     | Gate-to-Drain Charge                                | —    | 15.8 | —    |       |   |
| Q <sub>godr</sub>                   | Gate Charge Overdrive                               | —    | 21   | —    |       |   |
| Q <sub>sw</sub>                     | Switch Charge (Q <sub>gs2</sub> + Q <sub>gd</sub> ) | —    | 19   | —    |       |   |
| Q <sub>oss</sub>                    | Output Charge                                       | —    | 160  | —    | nC    | V <sub>DS</sub> = 50V, V <sub>GS</sub> = 0V   |
| R <sub>G</sub>                      | Gate Resistance                                     | —    | 0.9  | —    | Ω     |   |
| t <sub>d(on)</sub>                  | Turn-On Delay Time                                  | —    | 6.1  | —    | ns    | V <sub>DD</sub> = 50V, V <sub>GS</sub> = 10V<br>I <sub>D</sub> = 50A<br>R <sub>G</sub> = 1.0Ω |
| t <sub>r</sub>                      | Rise Time   | —    | 6.2  | —    |       |   |
| t <sub>d(off)</sub>                 | Turn-Off Delay Time                                 | —    | 15   | —    |       |   |
| t <sub>f</sub>                      | Fall Time   | —    | 5.3  | —    |       |   |
| C <sub>iss</sub>                    | Input Capacitance                                   | —    | 3120 | —    | pF    | V <sub>GS</sub> = 0V<br>V <sub>DS</sub> = 50V<br>f = 1.0MHz                                   |
| C <sub>oss</sub>                    | Output Capacitance                                  | —    | 1440 | —    |       |   |
| C <sub>rss</sub>                    | Reverse Transfer Capacitance                        | —    | 14   | —    |       |   |

**Diode Characteristics**

|                 | Parameter                              | Min. | Typ. | Max. | Units | Conditions   |
|-----------------|--|------|------|------|-------|--|
| I <sub>S</sub>  | Continuous Source Current (Body Diode) | —    | —    | 157  | A     | MOSFET symbol showing the integral reverse p-n junction diode.  |
| I <sub>SM</sub> | Pulsed Source Current (Body Diode) ①   | —    | —    | 320  |       |  |
| V <sub>SD</sub> | Diode Forward Voltage                  | —    | 0.8  | 1.3  | V     | T <sub>J</sub> = 25°C, I <sub>S</sub> = 50A, V <sub>GS</sub> = 0V ③  |
| t <sub>rr</sub> | Reverse Recovery Time                  | —    | 65   | 98   | ns    | T <sub>J</sub> = 25°C, I <sub>F</sub> = 50A, V <sub>DD</sub> = 50V   |
| Q <sub>rr</sub> | Reverse Recovery Charge                | —    | 113  | 170  | nC    | di/dt = 100A/μs ③  |

**Avalanche Characteristics**

|                                     | Parameter                       | Typ. | Max. | Units |
|-------------------------------------|---------------------------------|------|------|-------|
| E <sub>AS</sub> (Thermally limited) | Single Pulse Avalanche Energy ② | —    | 728  | mJ    |
| I <sub>AR</sub>                     | Avalanche Current ①             | —    | 38   | A     |

**Thermal Resistance**

|                           | Parameter             | Typ. | Max. | Units |
|---------------------------|-----------------------|------|------|-------|
| R <sub>θJC</sub> (Bottom) | Junction-to-Case ④    | —    | 0.64 | °C/W  |
| R <sub>θJC</sub> (Top)    | Junction-to-Case ④    | —    | 15   |       |
| R <sub>θJA</sub>          | Junction-to-Ambient ⑤ | —    | 31   |       |
| R <sub>θJA</sub> (<10s)   | Junction-to-Ambient ⑤ | —    | 19   |       |

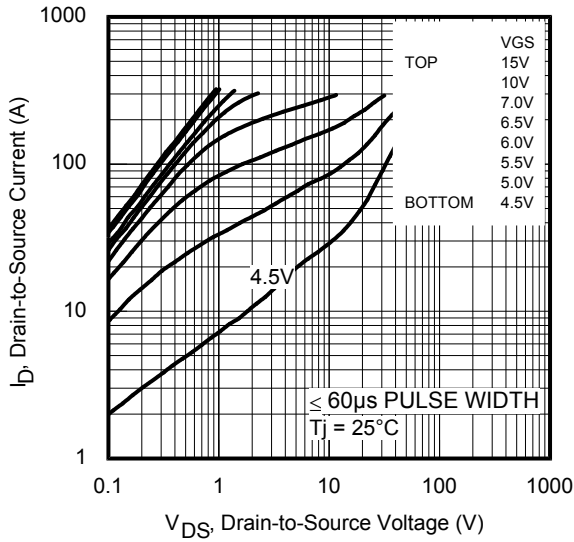


Fig 1. Typical Output Characteristics

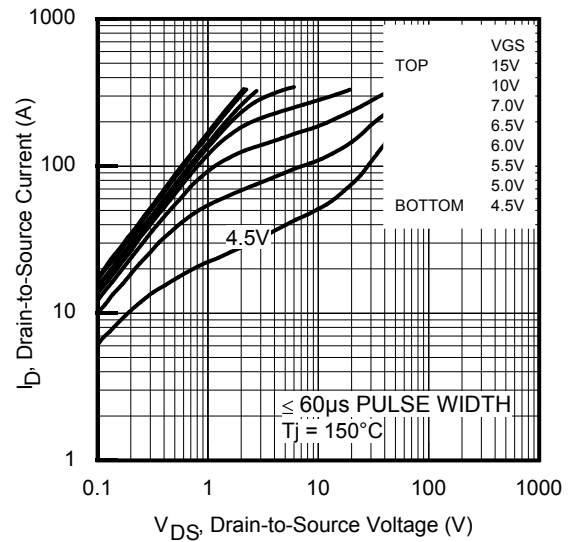


Fig 2. Typical Output Characteristics

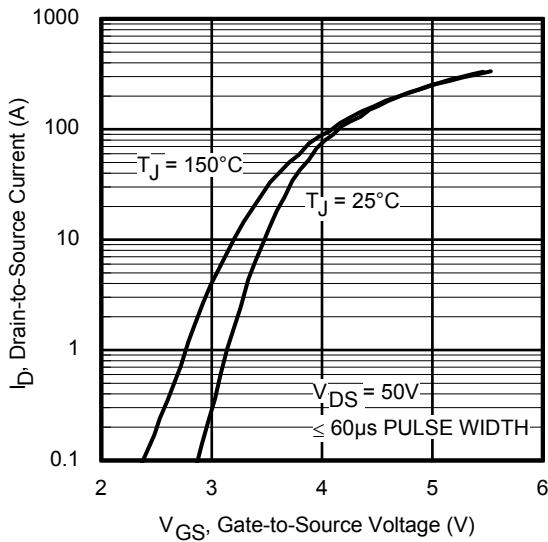


Fig 3. Typical Transfer Characteristics

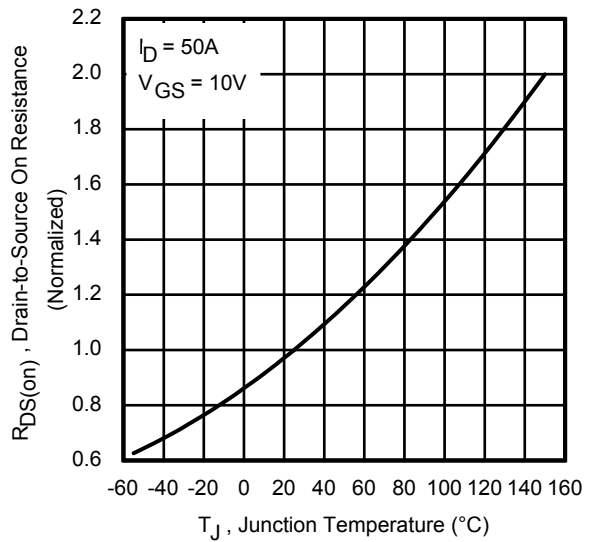


Fig 4. Normalized On-Resistance vs. Temperature

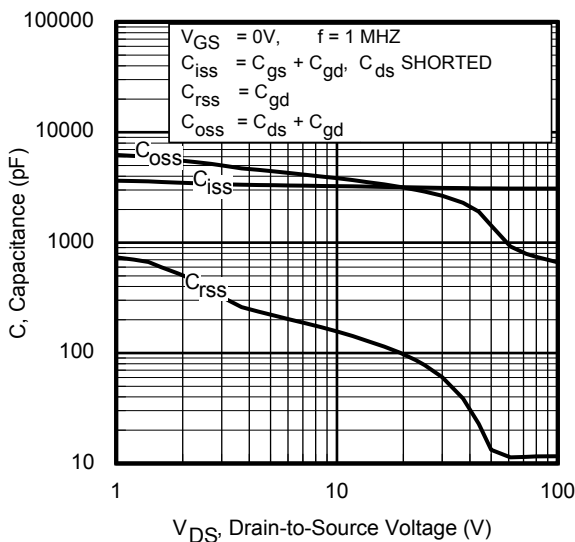


Fig 5. Typical Capacitance vs. Drain-to-Source Voltage

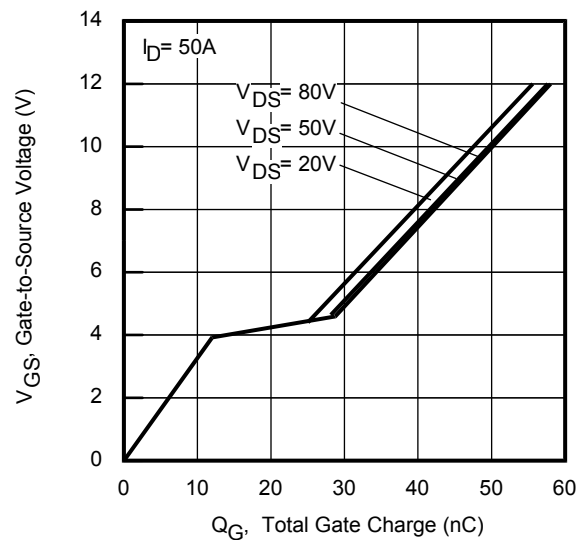
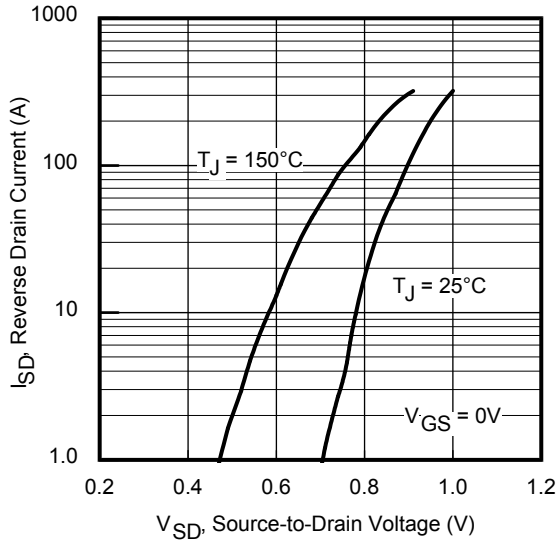
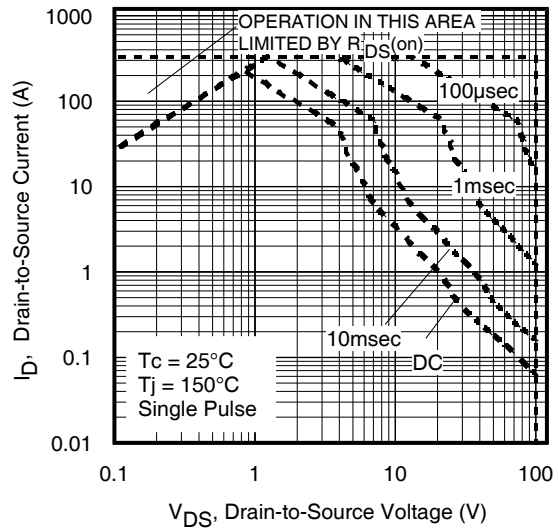
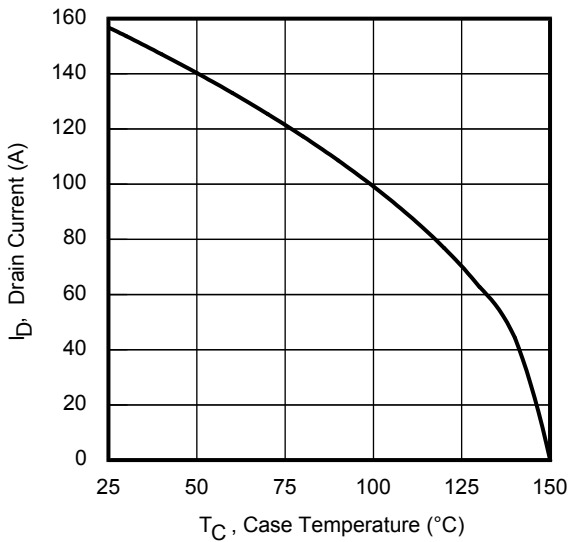
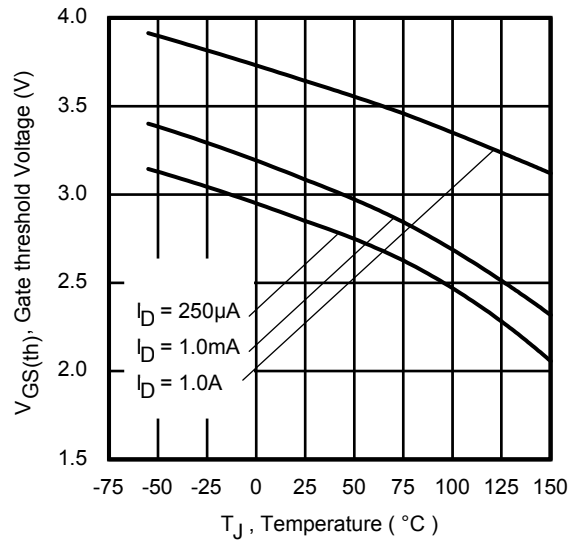
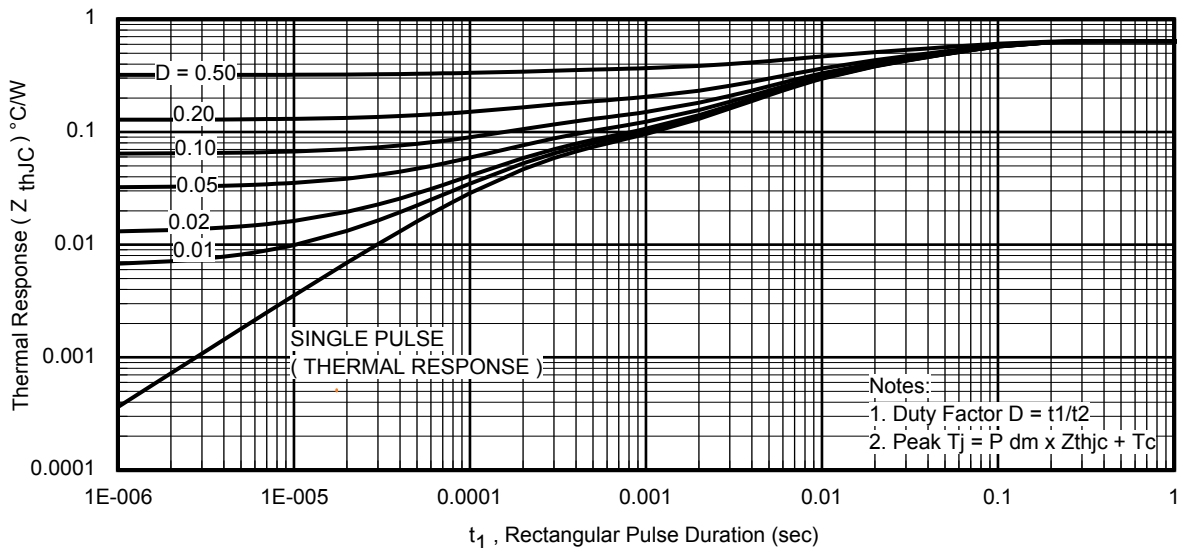


Fig 6. Typical Gate Charge vs. Gate-to-Source Voltage


**Fig 7.** Typical Source-Drain Diode Forward Voltage

**Fig 8.** Maximum Safe Operating Area

**Fig 9.** Maximum Drain Current vs. Case Temperature

**Fig 10.** Threshold Voltage vs. Temperature

**Fig 11.** Maximum Effective Transient Thermal Impedance, Junction-to-Case

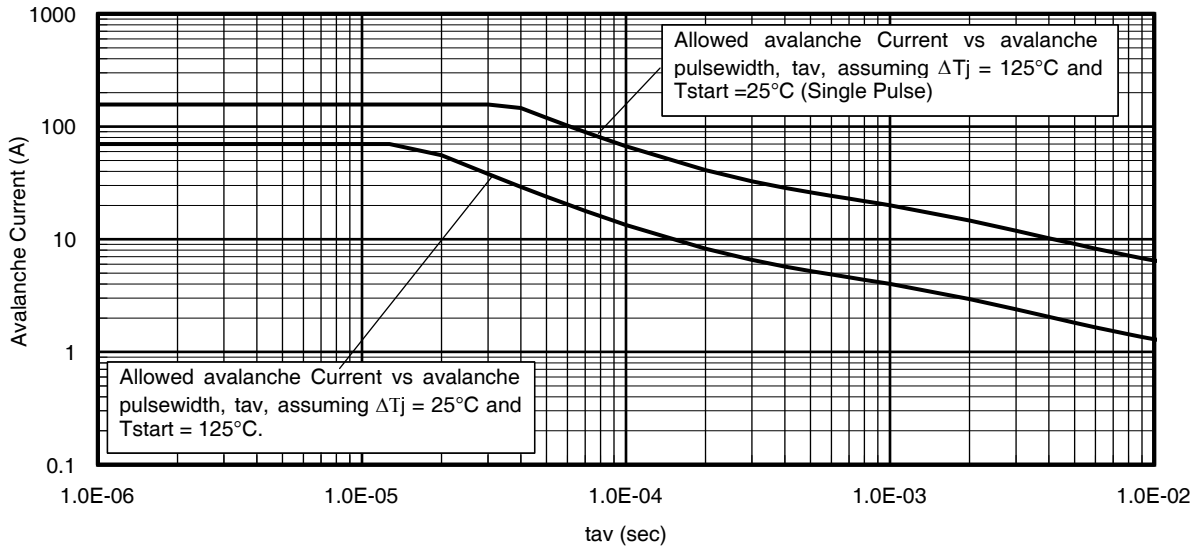


Fig 12. Typical Avalanche Current vs. Pulse Width

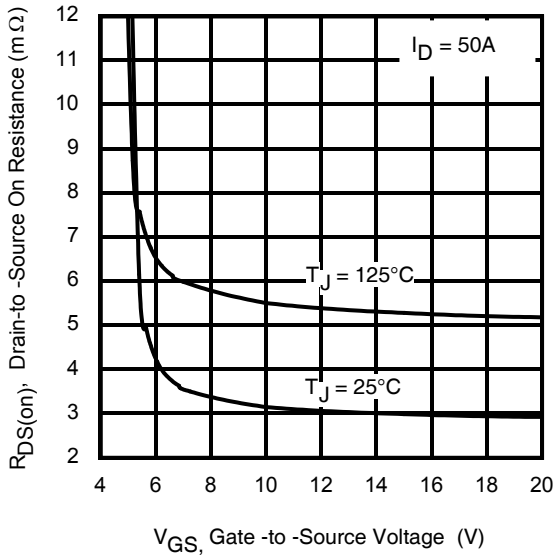


Fig 13. On-Resistance vs. Gate Voltage

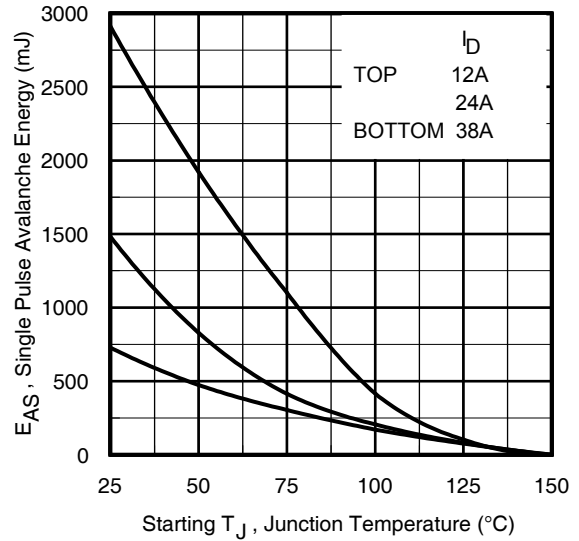
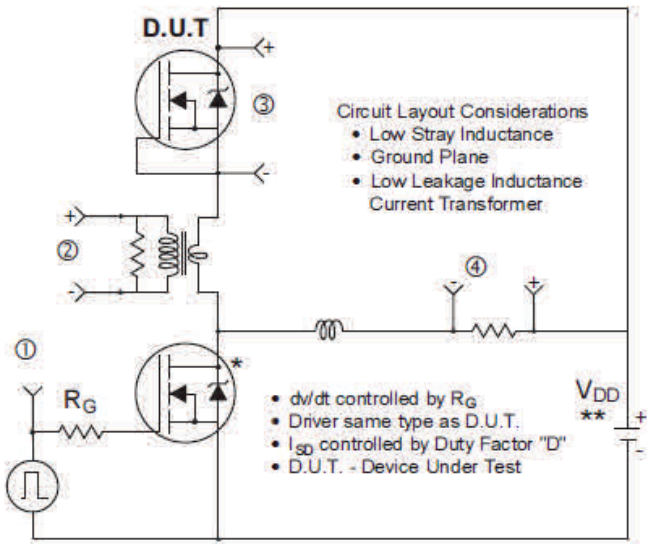
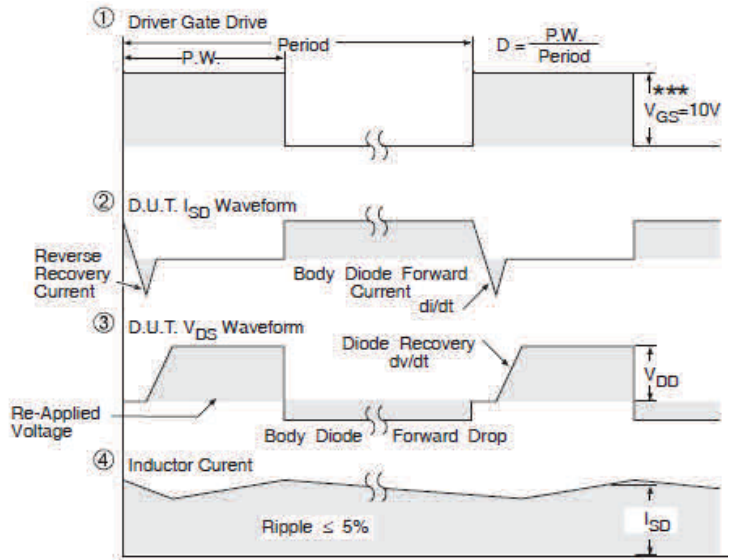


Fig 14. Maximum Avalanche Energy vs. Drain Current

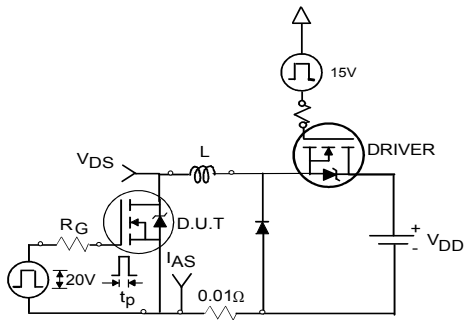


\* Use P-Channel Driver for P-Channel Measurements  
 \*\* Reverse Polarity for P-Channel

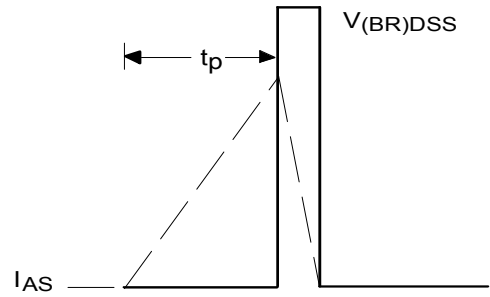


\*\*\*  $V_{GS} = 5V$  for Logic Level Devices

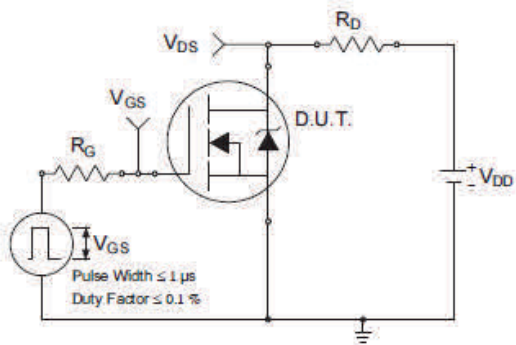
**Fig 15. Peak Diode Recovery dv/dt Test Circuit for N-Channel HEXFET® Power MOSFETs**



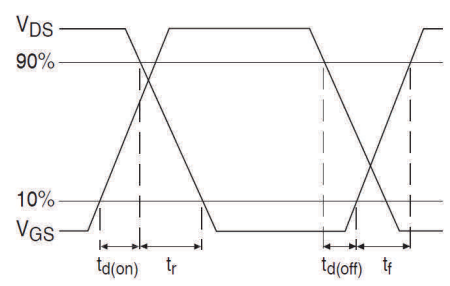
**Fig 16a. Unclamped Inductive Test Circuit**



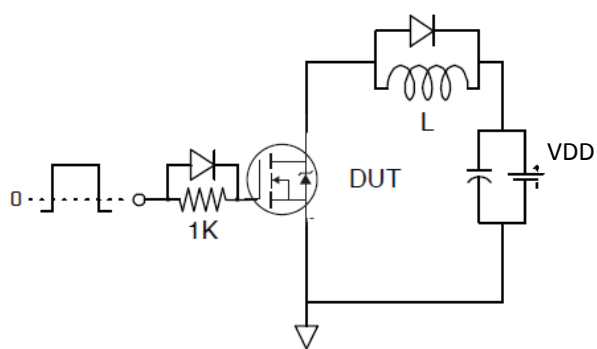
**Fig 16b. Unclamped Inductive Waveforms**



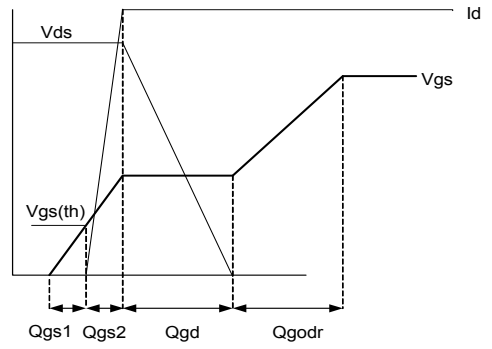
**Fig 17a. Switching Time Test Circuit**



**Fig 17b. Switching Time Waveforms**

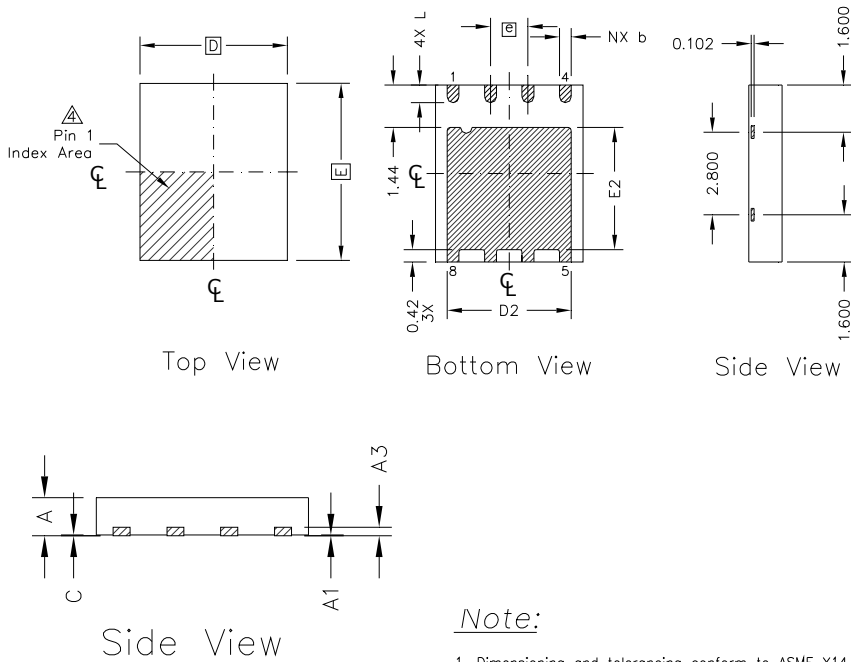


**Fig 18. Gate Charge Test Circuit**



**Fig 19. Gate Charge Waveform**

**PQFN 5x6 Outline "F" Package Details**



| SYMBOL | DIMENSIONS |       |       |
|--------|------------|-------|-------|
|        | MIN.       | NOM.  | MAX.  |
| A      | 0.80       | 0.90  | 1.00  |
| A1     | 0.000      | 0.02  | 0.05  |
| A3     | 0.203 Ref  |       |       |
| b      | 0.30       | 0.40  | 0.50  |
| D      | 5.00 BSC   |       |       |
| E      | 6.00 BSC   |       |       |
| e      | 1.27 BSC   |       |       |
| D2     | 4.06       | 4.21  | 4.31  |
| E2     | 3.988      | 4.138 | 4.238 |
| L      | 0.50       | 0.60  | 0.70  |
| aaa    | 0.05       |       |       |
| bbb    | 0.10       |       |       |
| ccc    | 0.10       |       |       |
| ddd    | 0.05       |       |       |
| eee    | 0.08       |       |       |
| N      | 8          |       |       |
| ND     | 4          |       |       |

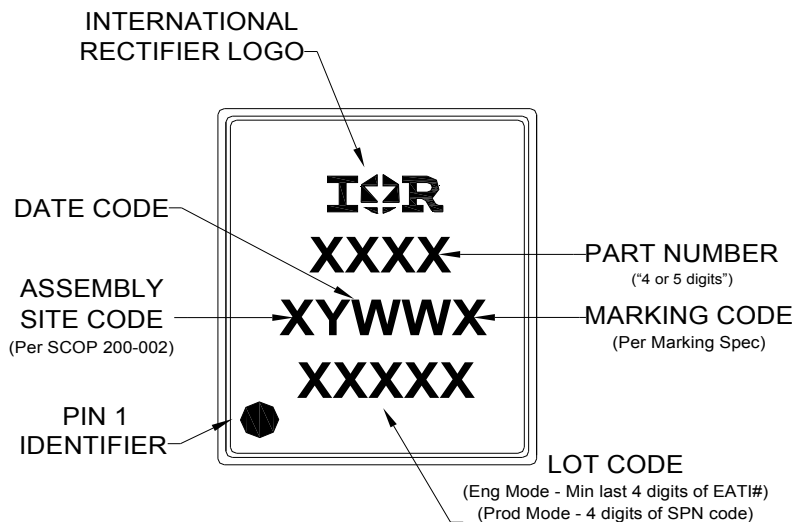
*Note:*

1. Dimensioning and tolerancing conform to ASME Y14.5-2009.
2. All dimensions are in millimeters.
3. N is the total number of terminals.
4. The location of the marked terminal #1 identifier is within the hatched area.
5. ND refers to the maximum number of terminals on D side.
6. Dimension b applies to the metallized terminal and is measured between 0.15mm and 0.30mm from the terminal tip. If the terminal has a radius on the other end of it, dimension b should not be measured in that radius area.
7. Coplanarity applies to the terminals and all other bottom surface metallization.

For more information on board mounting, including footprint and stencil recommendation, please refer to application note AN-1136: <http://www.irf.com/technical-info/appnotes/an-1136.pdf>

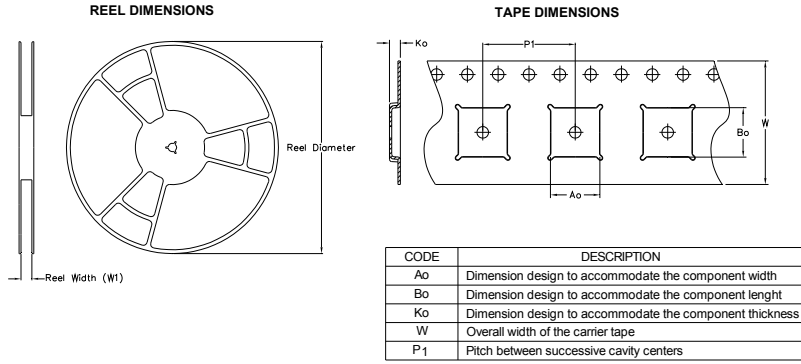
For more information on package inspection techniques, please refer to application note AN-1154: <http://www.irf.com/technical-info/appnotes/an-1154.pdf>

**PQFN 5x6 Outline "F" Part Marking**

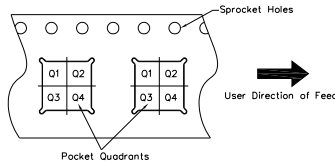


Note: For the most current drawing please refer to IR website at <http://www.irf.com/package/>

PQFN 5x6 Outline "F" Tape and Reel



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Note: All dimension are nominal

| Package Type | Reel Diameter (Inch) | QTY  | Reel Width W1 (mm) | Ao (mm) | Bo (mm) | Ko (mm) | P1 (mm) | W (mm) | Pin 1 Quadrant |
|--------------|----------------------|------|--------------------|---------|---------|---------|---------|--------|----------------|
| 5 X 6 PQFN   | 13                   | 4000 | 12.4               | 6.300   | 5.300   | 1.20    | 8.00    | 12     | Q1             |

Note: For the most current drawing please refer to IR website at <http://www.irf.com/package/>

Qualification Information<sup>†</sup>

|                                   |  |   |
|-----------------------------------|--|---|
| <b>Qualification Level</b>        | Industrial<br>(per JEDEC JESD47F <sup>††</sup> guidelines) |   |
| <b>Moisture Sensitivity Level</b> | PQFN 5mm x 6mm   | MSL1<br>(per JEDEC J-STD-020D <sup>††</sup> ) |
| <b>RoHS Compliant</b>             | Yes  |   |

† Qualification standards can be found at International Rectifier's web site: <http://www.irf.com/product-info/reliability/>

†† Applicable version of JEDEC standard at the time of product release.

Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Starting  $T_J = 25^\circ\text{C}$ ,  $L = 1\text{mH}$ ,  $R_G = 50\Omega$ ,  $I_{AS} = 38\text{A}$ .
- ③ Pulse width  $\leq 400\mu\text{s}$ ; duty cycle  $\leq 2\%$ .
- ④  $R_\theta$  is measured at  $T_J$  of approximately  $90^\circ\text{C}$ .
- ⑤ When mounted on 1 inch square PCB (FR-4). Please refer to AN-994 for more details: <http://www.irf.com/technical-info/appnotes/an-994.pdf>



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